

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3395538

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHAO ZHENG	06/08/2015
WEI WANG	06/08/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
<b>Street Address:</b>	18 ZHANGJIANG ROAD
<b>Internal Address:</b>	PUDONG NEW AREA
<b>City:</b>	SHANGHAI
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	201203
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14738582
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(408)638-0326
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	408 331 1670
<b>Email:</b>	jfosnaugh@innovationcounsel.com
<b>Correspondent Name:</b>	INNOVATION COUNSEL LLP
<b>Address Line 1:</b>	2880 LAKESIDE DRIVE
<b>Address Line 2:</b>	SUITE 200
<b>Address Line 4:</b>	SANTA CLARA, CALIFORNIA 95054-2818
<b>ATTORNEY DOCKET NUMBER:</b>	PCAS00042 US
<b>NAME OF SUBMITTER:</b>	KIEUN SUNG, REG. NO. 48,639
<b>SIGNATURE:</b>	/Kieun Sung/
<b>DATE SIGNED:</b>	06/12/2015
<b>Total Attachments: 1</b>	
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CLIENT REFERENCE NO.: 2014-00924 -SH-US  
ATTORNEY DOCKET NO.: PCAS00042 US

**ASSIGNMENT**

For good and valuable consideration, receipt of which is hereby acknowledged, we

Chao ZHENG of 18 Zhangjiang Road  
Pudong New Area  
Shanghai, P.R.C. 201203  
Wei WANG of 18 Zhangjiang Road  
Pudong New Area  
Shanghai, P.R.C. 201203

hereby sell, assign and transfer to **Semiconductor Manufacturing International (Shanghai) Corporation**, having a place of business at 18 Zhangjiang Road, Pudong New Area, Shanghai, P.R.C. 201203, its successors and assigns, the entire right, title and interest throughout the world in our invention in

**A SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME**

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisionals, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

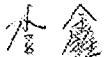
Executed this 8th day of June, 2015.



Chao ZHENG

WITNESSED:

Signature

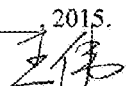


Date

2015-06-08

Type or print name of witness


Executed this 8th day of June, 2015.



Wei WANG

WITNESSED:

Signature



Date

2015-06-08

Type or print name of witness